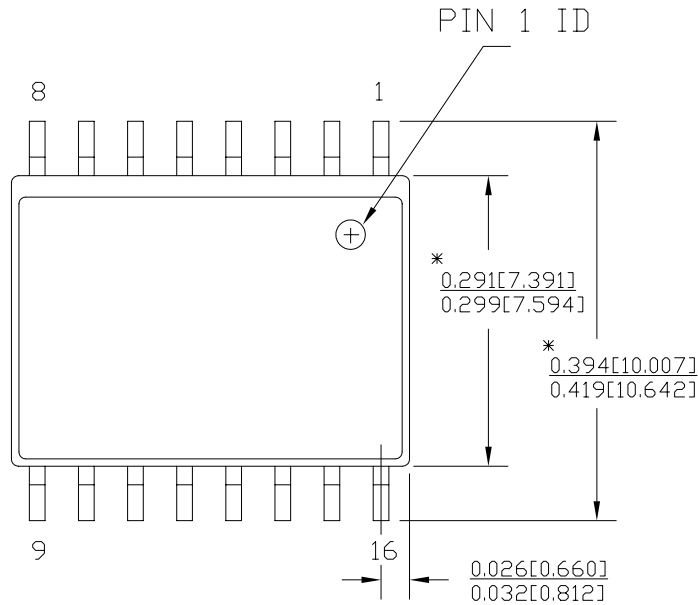


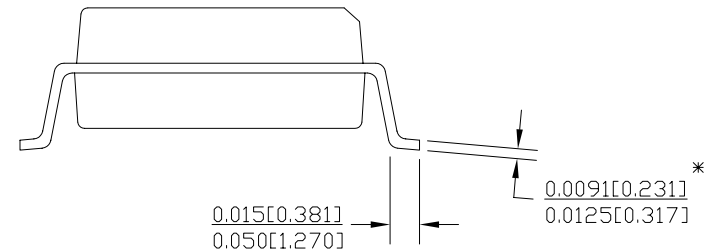
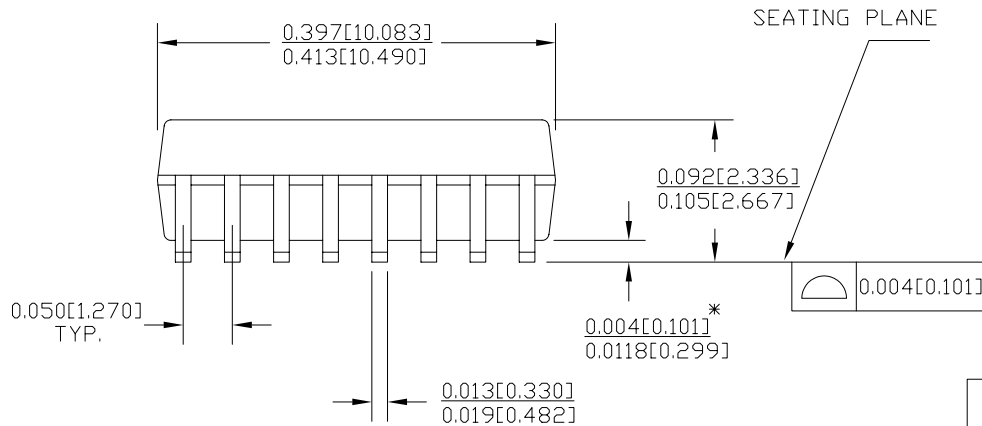
16 Lead (300 Mil) SOIC - S1

REVISIONS						
PAGE	ZONE	REV	ECN	DESCRIPTION	DATE	APPROVED
1	-	**	N/A	N/A	N/A	N/A
1	-	*A	49379	CHG. TITLE/ CHG. DIM.S AT *	04/08/97	N/A
1	-	*B	128905	ADD MM DIM./ADD JEDEC #/ADD SZ PART #.	08/04/03	HTN
1	-	*C	2868899	CHANGED TEMPLATE, CHANGE TITLE FROM 16LD (300 MIL) SOIC PKG OUTLINE TO PACKAGE OUTLINE, 16L SOIC .413X.299X.0932 INCHES	01/28/10	QAD



DIMENSIONS IN INCHES[MM] MIN.
MAX.
REFERENCE JEDEC MO-119

PART #	
S16.3	STANDARD PKG.
SZ16.3	LEAD FREE PKG.



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UNLESS OTHERWISE SPECIFIED ALL DIMENSIONS ARE IN MILLIMETERS STANDARD TOLERANCES ON: DECIMALS .XX ± 0.05 .XXX ± .XXXX + ANGLES ± 1°	DESIGNED BY	N/A	DATE	N/A	CYPRESS Company Confidential				
	DRAWN BY	HTN	DATE	08/04/03					
	CHECKED BY	TSV	DATE	01/28/10					
	APPROVED BY	QAD	DATE	01/28/10					
MATERIAL	N/A	APPROVED BY	JGUA	DATE	01/28/10	TITLE	PACKAGE OUTLINE, 16L SOIC .413X.299X.0932 INCHES		
FINISH	N/A	APPROVED BY	N/A	DATE	N/A	SIZE	PART NO.	DWG NO	REV
						A	SEE NOTE	51-85022	*C
						SCALED TO FIT	N/A	SHEET	1 OF 1